

P-Channel Enhancement Mode MOSFET

Feature

Pin Description

- -30V/-46A
R_{DS(ON)} = 12 m (typ.) @V_{GS} = -10V
R_{DS(ON)} = 18 m (typ.) @V_{GS} = -4.5V
- 100% Avalanche Tested
- 100% DVDS
- Reliable and Rugged
- Halogen Free and Green Devices Available
(RoHS Compliant)

Applications

- Switching application
- Li-battery protection
- DC-DC

Ordering and Marking Information

HYG 130P03LQ XYMXXXXX	Package Code D: TO-252-2L U: TO-251-3L V: TO-251-3S Date Code XYMXXXXXX
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Absolute Maximum Ratings

Symbol	Parameter	Rating	Unit	
Common Ratings (Tc=25°C Unless Otherwise Noted)				
V _{DSS}	Drain-Source Voltage	-30	V	
V _{GSS}	Gate-Source Voltage	20	V	
T _J	Junction Temperature Range	-55 to 175	°C	
T _{STG}	Storage Temperature Range		°C	
I _S	Source Current-Continuous(Body Diode)	Tc=25°C	-46	A
Mounted on Large Heat Sink				
I _{DM}	Pulsed Drain Current *	Tc=25°C	-165	A
I _D	Continuous Drain Current	Tc=25°C	-46	A
		Tc=100°C	-33	A
P _D	Maximum Power Dissipation	Tc=25°C	60	W
		Tc=100°C	30	W
R _{JC}	Thermal Resistance, Junction-to-Case		2.5	°C/W
R _{JA}	Thermal Resistance, Junction-to-Ambient **		75	°C/W
E _{AS}	Single Pulsed-Avalanche Energy ***	L=0.3mH	88	mJ

Note: * Repetitive rating pulse width limited by max.junction temperature.

** Surface mounted on 1in2 FR-4 board.

*** Limited by T_{Jmax}, starting T_J=25°C, L = 0.3mH, R_e= 25 , V_{GS} =-10V.

Electrical Characteristics(Tc =25°C Unless Otherwise Noted) 14 306.53 0.48 0.48 16.5 Tc 024 290.93 0.48 2 16.5

Symbol	Parameter	Test Conditions	HYG130P03LQ1			Unit
			Min	Typ.	Max	

Electrical Characteristics (Cont.) (Tc =25°C Unless Otherwise Noted)

Symbol	Parameter	Test Conditions	HYG130P03LQ1			Unit
			Min	Typ.	Max	
Dynamic Characteristics						
R _G	Gate Resistance	V _{GS} =0V, V _{DS} =0V, F=1MHz	-	4.9	-	
C _{iss}	Input Capacitance	V _{GS} =0V, V _{DS} =-25V, Frequency=1MHz	-	1400	-	pF
C _{oss}	Output Capacitance					
C _{rss}	Reverse Transfer Capacitance					
t _{d(ON)}	Turn-on Delay Time	V _{DD} =-15V, R _G =2.5 Ω, I _{DS} =-15A, V _{GS} =-10V	-	8	-	ns
T _r	Turn-on Rise Time					
t _{d(OFF)}	Turn-off Delay Time					
T _f	Turn-off Fall Time					
Gate Charge Characteristics						
Q _g	Total Gate Charge(V _{GS} =-10V)	V _{DS} =-24V, I _{DS} =-15A	-	34	-	nC
	Total Gate Charge(V _{GS} =-4.5V)		-	17	-	
Q _{gs}	Gate-Source Charge		-	6	-	
Q _{gd}	Gate-Drain Charge		-	10	-	
V _{plateau}	Gate plateau voltage		-	4.0	-	V

Note: *Pulse test pulse width 300us duty cycle 2%

Typical Operating Characteristics

Figure 1: Power Dissipation

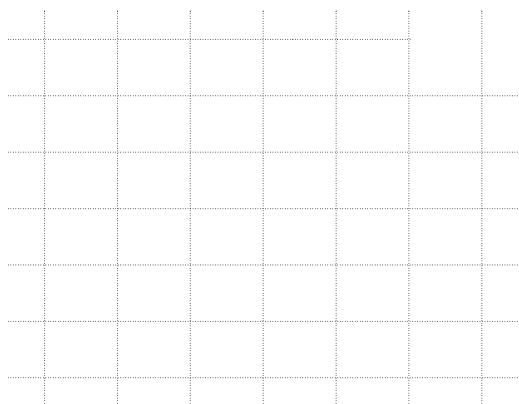


Figure 2: Drain Current

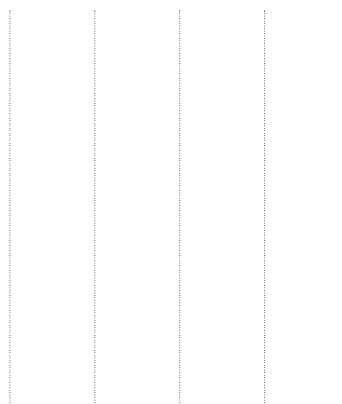


Figure 3: Safe Operation Area

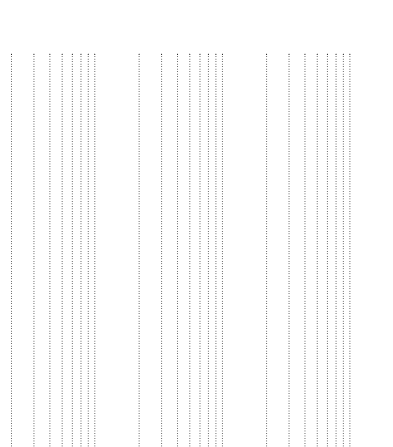


Figure 4: Thermal Transient Impedance

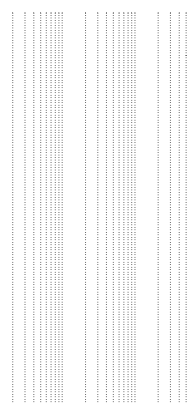


Figure 5: Output Characteristics

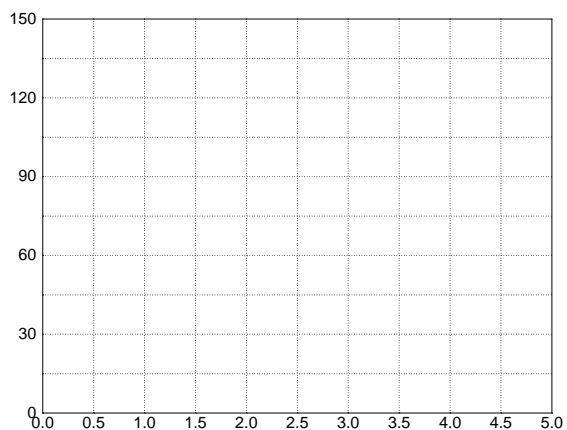


Figure 6: Drain-Source On Resistance



Typical Operating Characteristics(Cont.)

Figure 7: On-Resistance vs. Temperature

Figure 8: Source-Drain Diode Forward

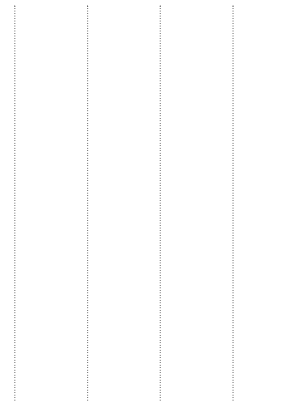
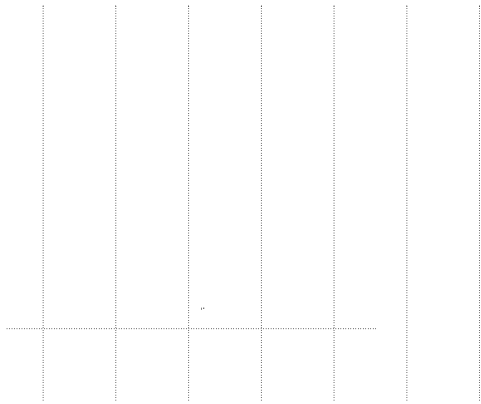
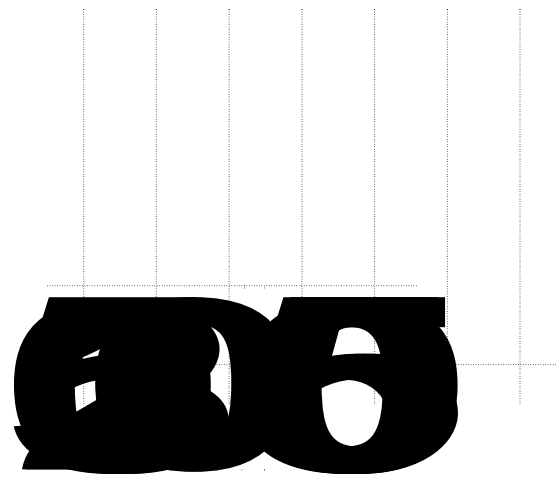
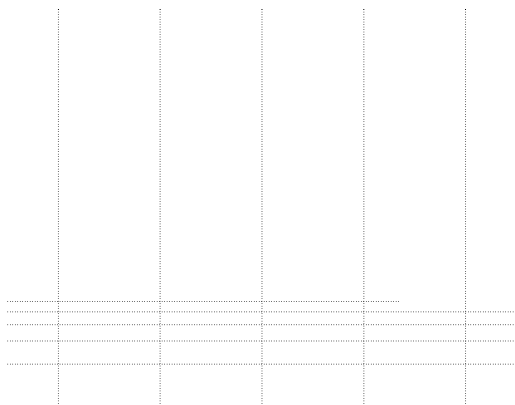
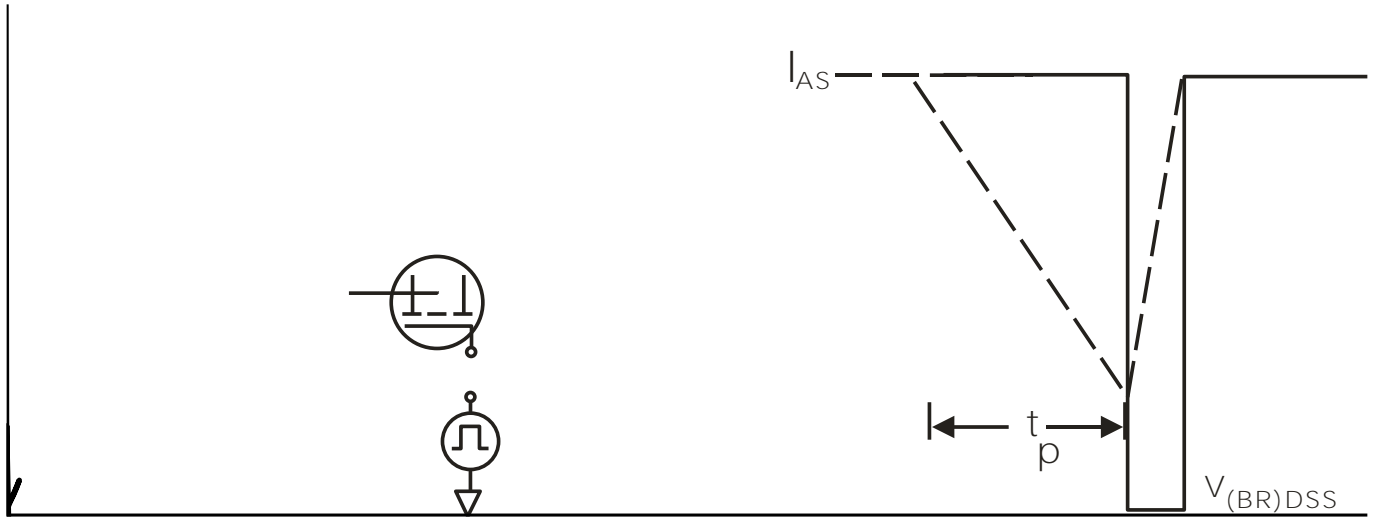


Figure 9: Capacitance Characteristics

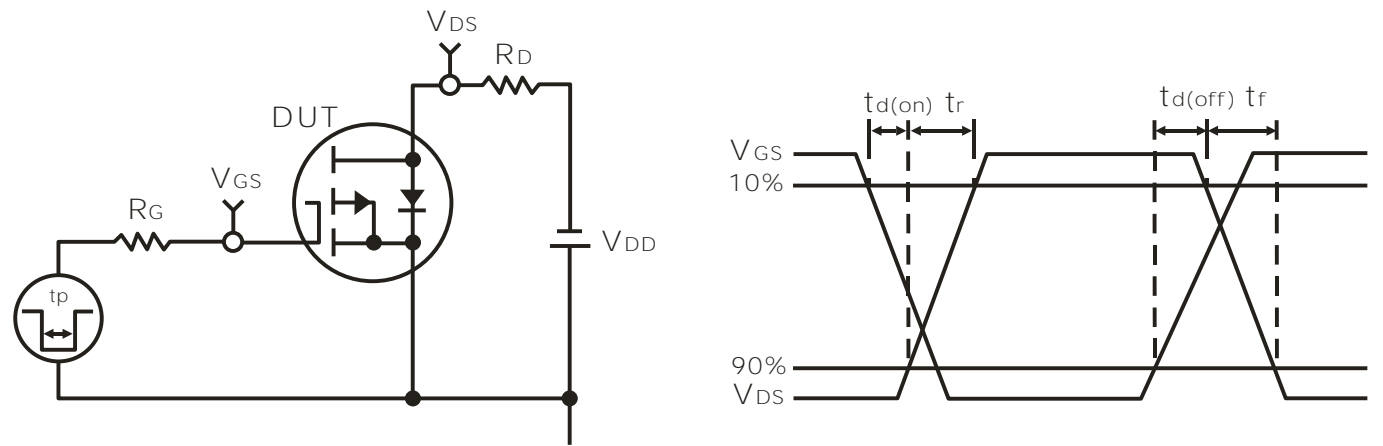
Figure 10: Gate Charge Characteristics



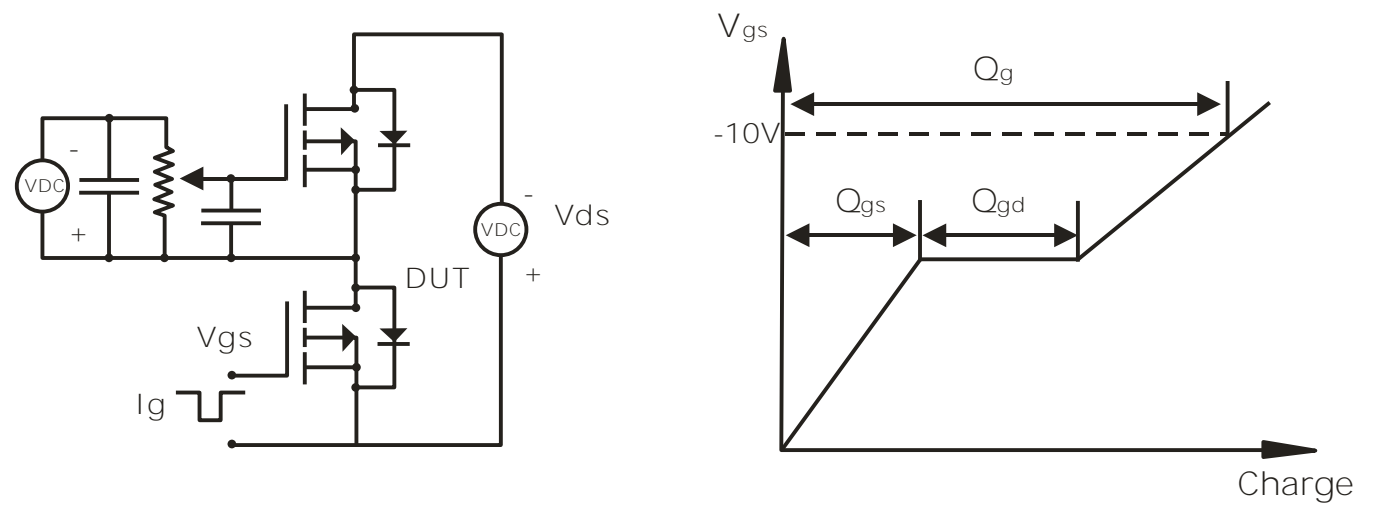
Avalanche Test Circuit



Switching Time Test Circuit



Gate Charge Test Circuit



Device Per Unit

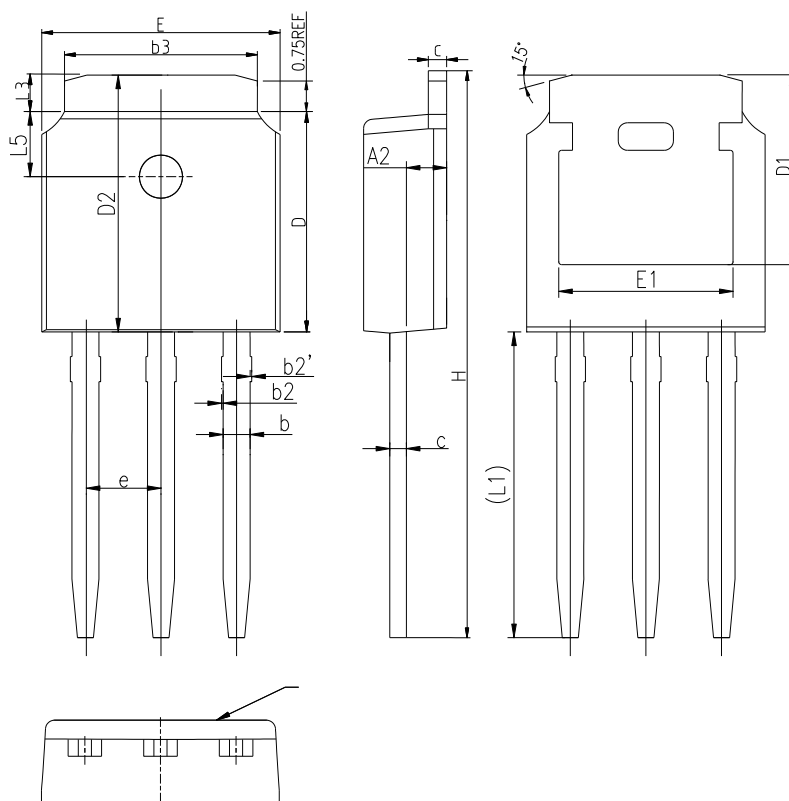
Package Type	Unit	Quantity
TO-252-2L	Tube	75
TO-252-2L	Reel	2500
TO-251-3L	Tube	75
TO-251-3S	Tube	75

Package Information

TO-252-2L

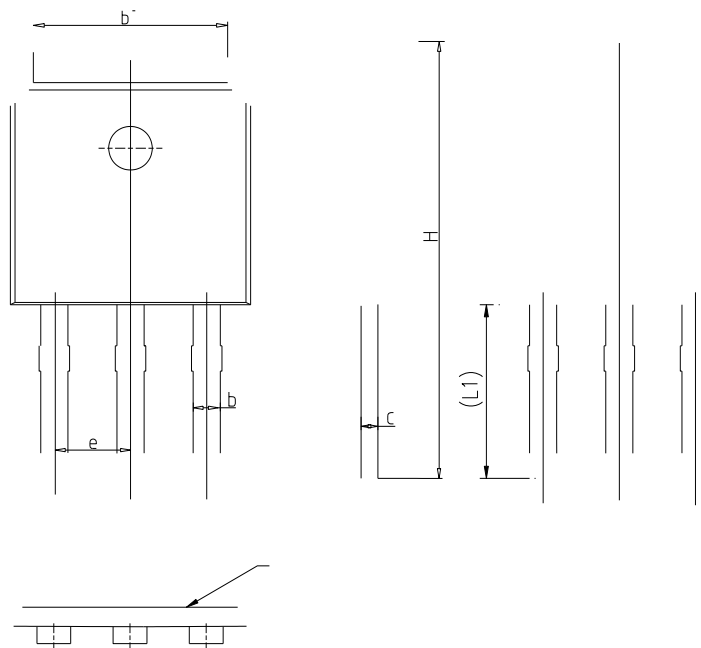
COMMON DIMENSIONS			
SYMBOL	mm		
	MIN	NOM	MAX
A	2.20	2.30	2.40
A1	0.00	-	0.12
A2	0.97	1.07	1.17
b	0.68	0.78	0.90
b3	5.20	5.33	5.46
c	0.43	0.53	0.61
D	5.98	6.10	6.22
D1	5.30REF		
E	6.40	6.60	6.73
E1	4.63	-	-
e	2.286BSC		
H	9.40	10.10	10.50
L	1.38	1.50	1.75
L1	2.90REF		
L2	0.51BSC		
L3	0.88	-	1.28
L4	0.50	-	1.00
L5	1.65	1.80	1.95
	0°	-	8°

TO-251-3L



COMMON DIMENSIONS			
SYMBOL	mm		
	MIN	NOM	MAX
A	2.20	2.30	2.38
A2	0.97	1.07	1.17
b	0.68	0.78	0.90
b2	0.00	0.04	0.10
b2'	0.00	0.04	0.10
b3	5.20	5.33	5.46
c	0.43	0.53	0.61
D	5.98	6.10	6.22
D1	4.30	5.30	6.00
D2	6.92	7.12	7.32
E	6.40	6.60	6.73
E1	4.63	-	-
e	2.286BSC		
H	16.22	16.52	16.82
L1	9.15	9.40	9.65
L3	0.88	1.02	1.28
L5	1.65	1.80	1.95

TO-251-3S



COMMON DIMENSIONS			
SYMBOL	mm		
	MIN	NOM	MAX
A	2.20	2.30	2.38
A2	0.97	1.07	1.17
b	0.68	0.78	0.90
b3	5.20	5.33	5.46
c	0.43	0.53	0.60
D	5.98	6.10	6.22
D1	5.30REF		
E	6.40	6.60	6.73
E1	4.63	-	-
e	2.286BSC		
H	10.00	11.22	11.44
L1	3.90	4.10	4.30
L3	0.88	1.02	1.28
L5	1.65	1.80	1.95

Classification Profile



Classification Reflow Profiles

Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
Preheat & Soak		
Temperature min (T_{smin})	100 °C	150 °C
Temperature max (T_{smax})	150 °C	200 °C
Time (T_{smin} to T_{smax}) (t_s)	60-120 seconds	60-120 seconds
Average ramp-up rate (T_{smax} to T_P)	3 °C/second max.	3°C/second max.
Liquidous temperature (T_L)	183 °C	217 °C
Time at liquidous (t_L)	60-150 seconds	60-150 seconds
Peak package body Temperature (T_P)*	See Classification Temp in table 1	See Classification Temp in table 2
Time (t_P)** within 5°C of the specified classification temperature (T_c)	20** seconds	30** seconds
Average ramp-down rate (T_P to T_{smax})	6 °C/second max.	6 °C/second max.
Time 25°C to peak temperature	6 minutes max.	8 minutes max.
*Tolerance for peak profile Temperature (T_P) is defined as a supplier minimum and a user maximum.		
** Tolerance for time at peak profile temperature (t_P) is defined as a supplier minimum and a user maximum.		

Table 1. Eutectic Process – Classification Temperatures (Tc)

Package Thickness	Volume <350	Volume 350-2000
2.5 mm	235 °C	220 °C
2.5 mm	220 °C	220 °C

Table 2. Pb-free Process – Classification Temperatures (Tc)

Package Thickness	Volume mm <350	Volume mm 350-2000	Volume mm >2000
2.5 mm	260 °C	260 °C	260 °C
2.5 mm	260 °C	260 °C	260 °C
2.5 mm	260 °C	260 °C	260 °C

Reliability Testing

Test item	Method	Description
SOLDERABILITY	JESD-22, B102	5 Sec, 245°C
HTRB	JESD-22, A108	168/500 Hrs, Bias @ 150°C
HTGB	JESD-22, A108	168 /500 Hrs, Vgs100% @ 150°C
PCT		